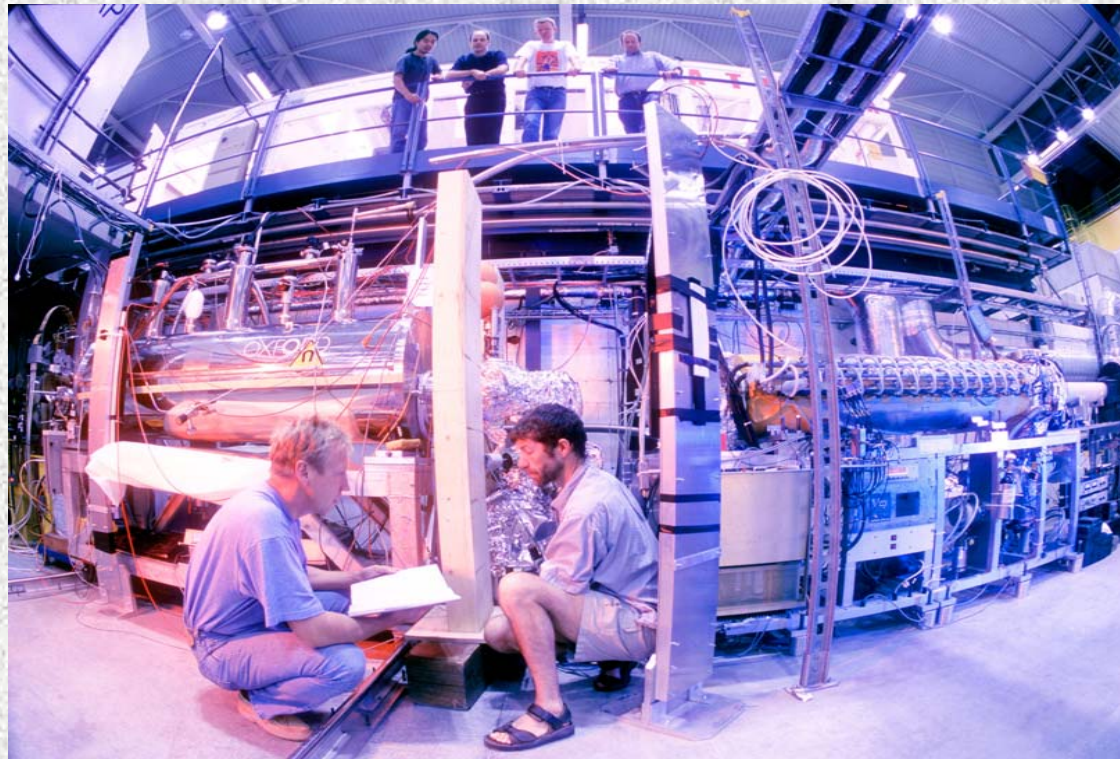


# ATHENA - Module Construction 1998-2000

P. Riedler\*, J. Rochet  
ATHENA Group, University of Zürich



\* now at CERN



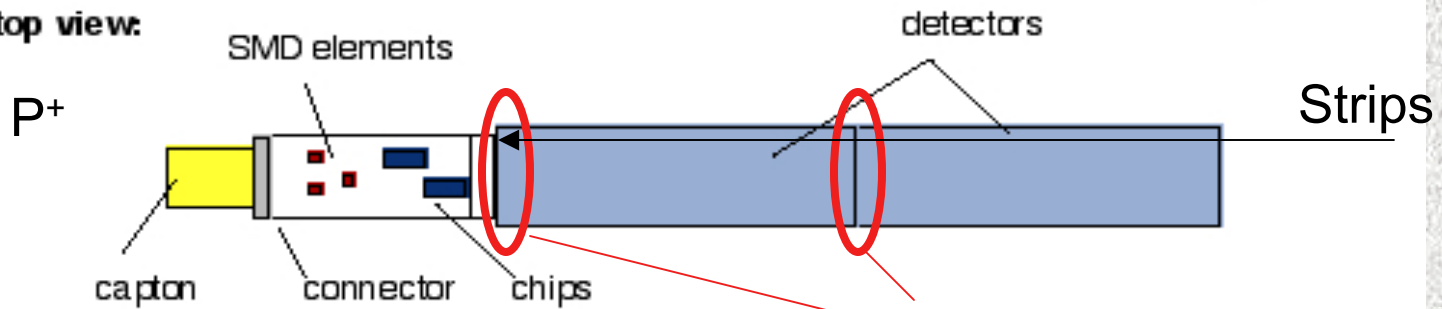
# ATHENA Silicon Vertex Detector

- Cylindrical symmetry
- Outer diameter: 139.7 mm
- Inner diameter: 75 mm
- Length: 241.1 mm
- Precision: +/- 15  $\mu\text{m}$
- **Temperature: 90-140K**
- **Vacuum:  $10^{-8}$  mbar**
- **3 T magnetic field**
- 16-fold symmetry
- 2 layers Si strip-detectors
- 192 CsI crystals with Si photodiodes
- 8960 read-out channels

# Double Sided Silicon Strip Detector Modules

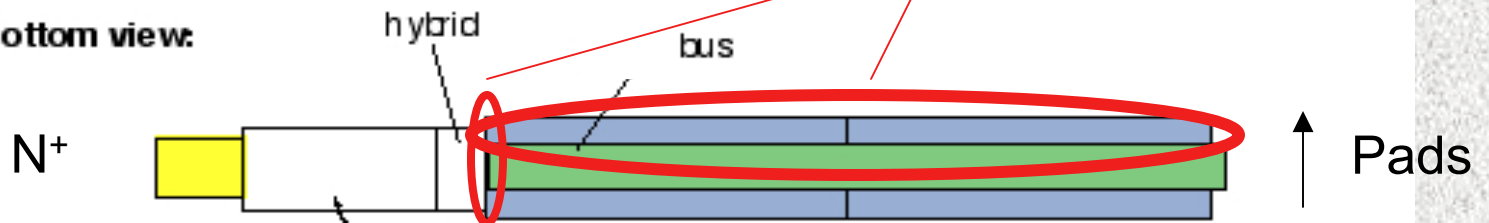


top view:



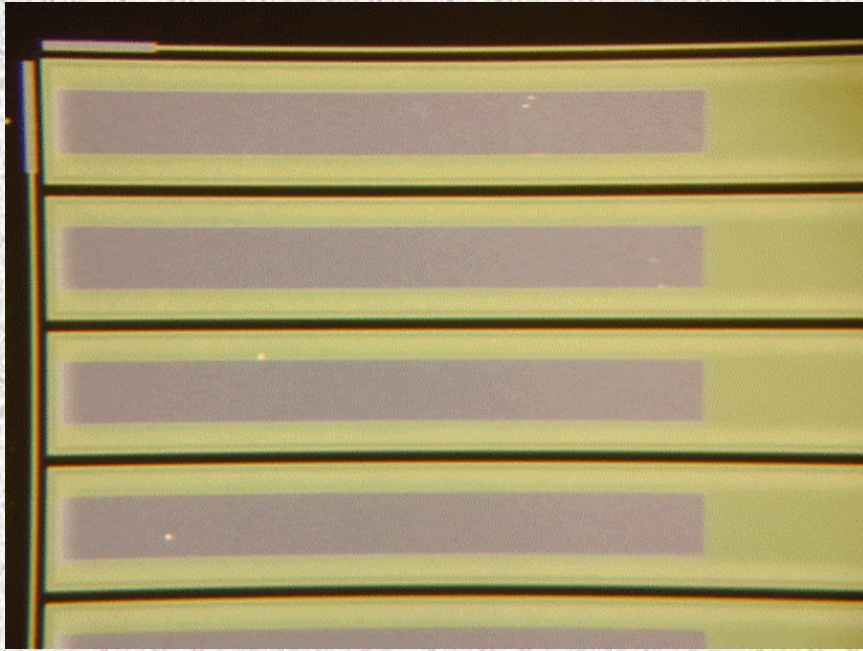
Wire bonds (25µm diam.)

bottom view:





# Bonding Pads

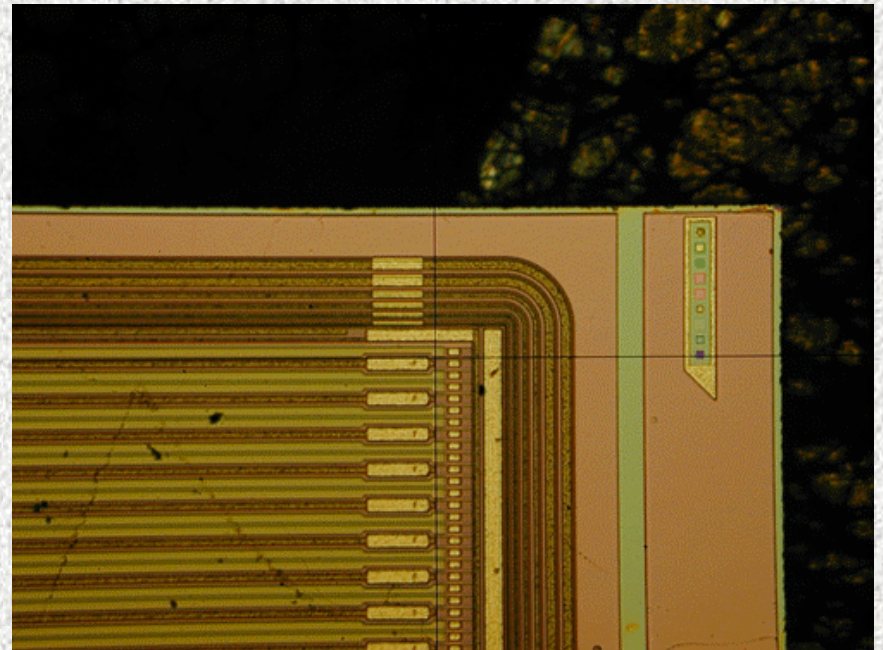


← **n<sup>+</sup> pads:**  
1mm wide  
1248 $\mu$ m pitch  
Bond pads: 500  $\mu$ m x 1mm

Bus was glued to this side

**P<sup>+</sup> side:** →

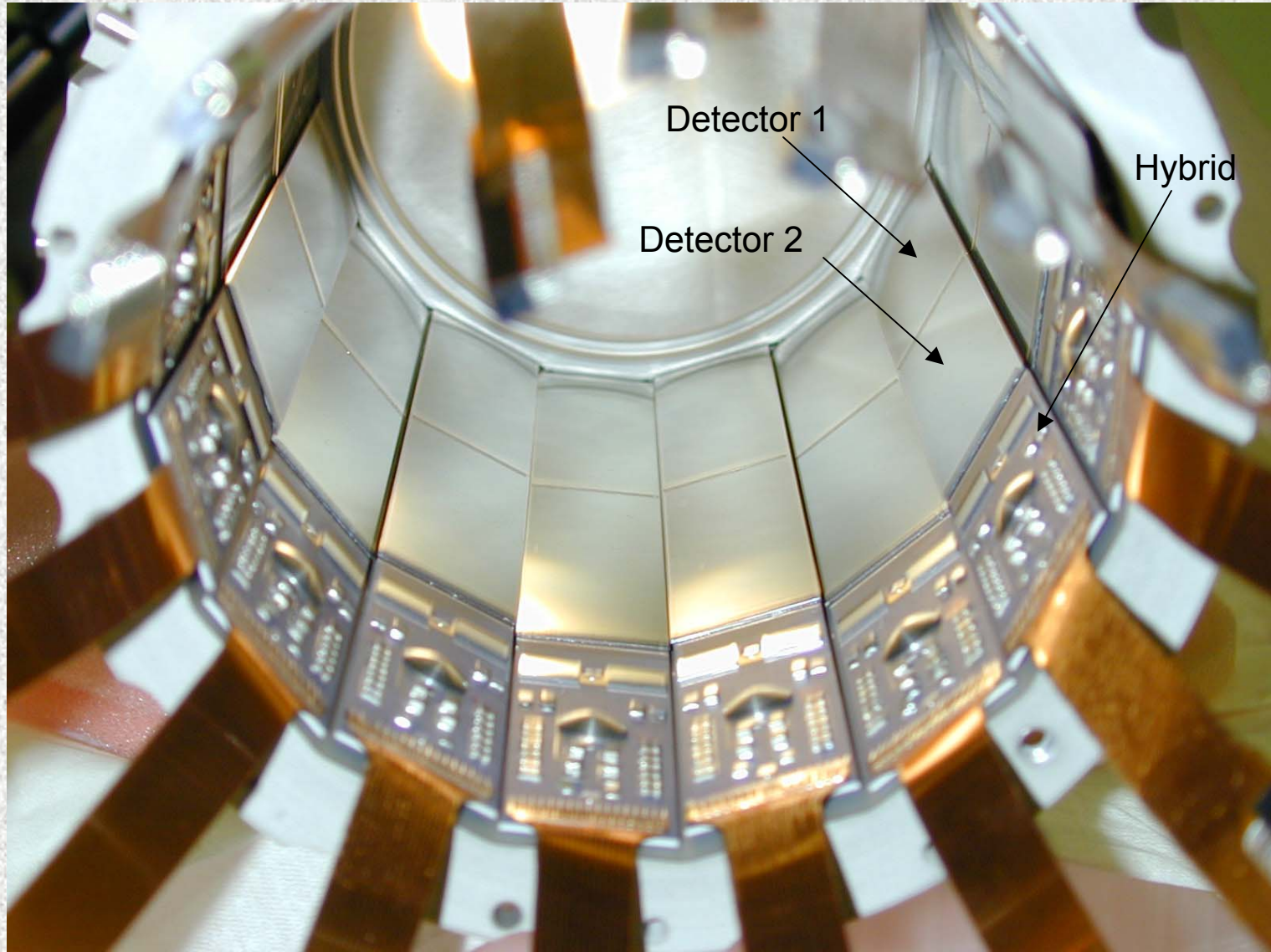
Bond pad: 60  $\mu$ m x 200  $\mu$ m  
140  $\mu$ m r.o. pitch (2 intermediate strips)



Bonding tested on sensors - ok!

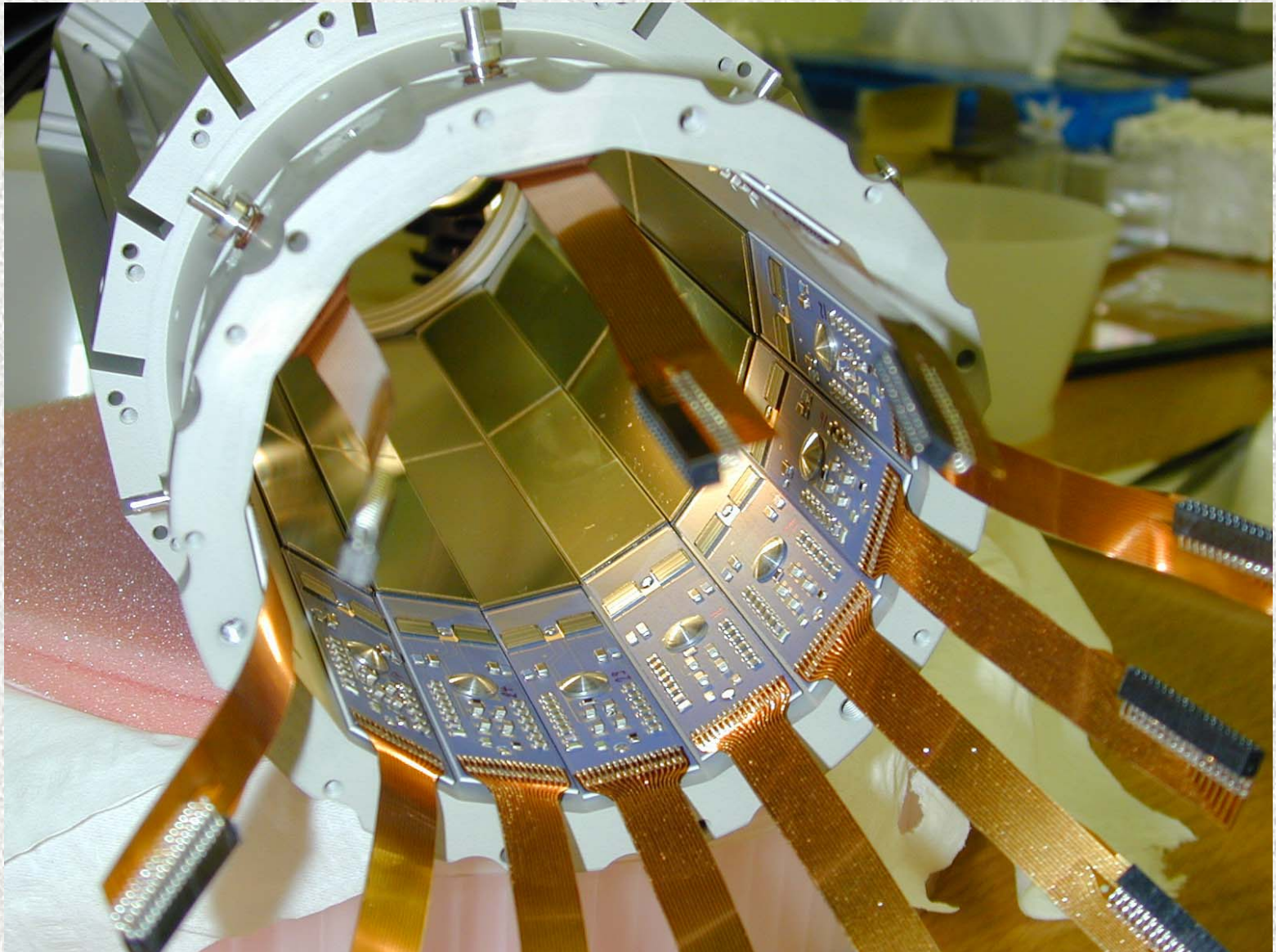


# Outer layer - 16 modules





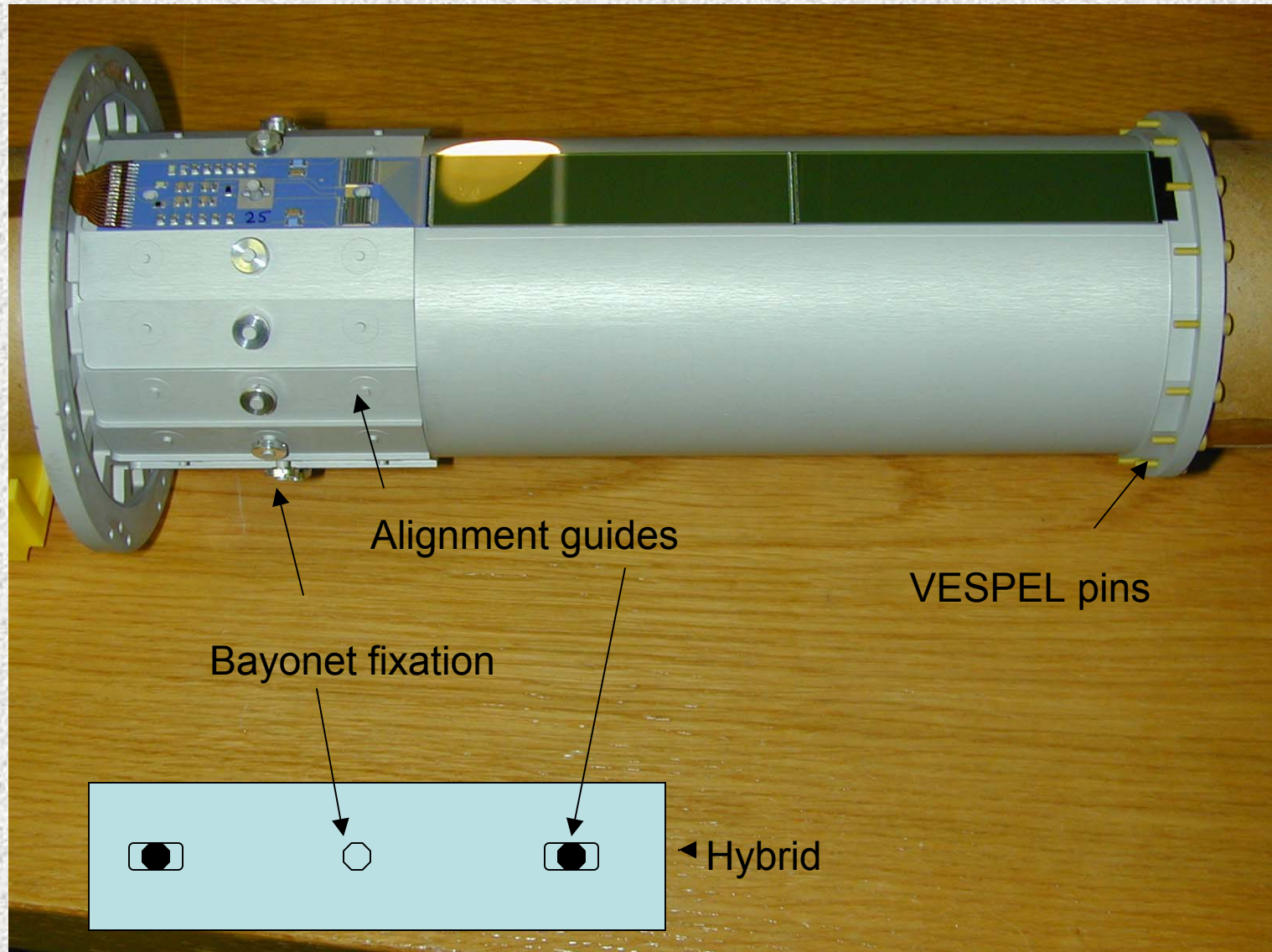
Outer layer mounted with bayonet fixation and spring compensator on AI support





Inner layer support

Modules mounted in wind-mill configuration (0.9 mm over-lapp)





## Constraints and Problems

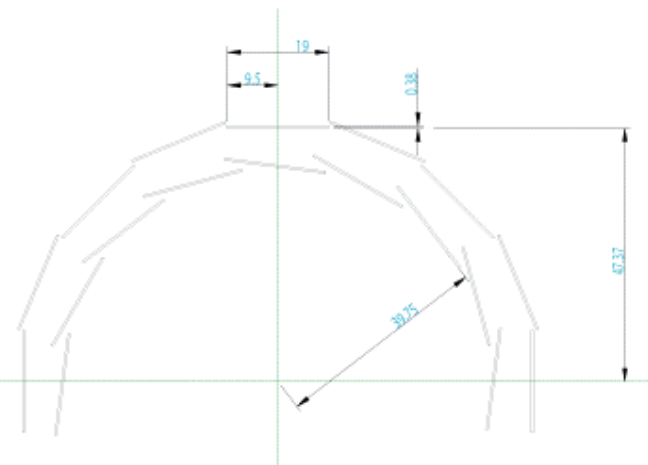
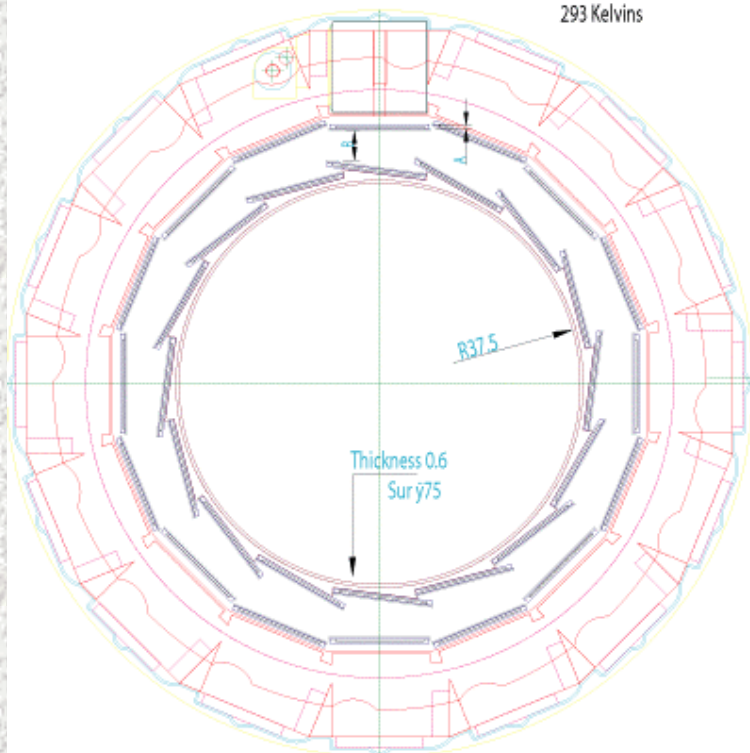
- **Double sided strip detectors**
  - o handling
  - o connections on both sides required
- **Special mounting jigs required for each assembly step+double sided bonding**
- **Temperature range: 90 K - 300 K**
  - o mechanical stability (different TEC) - BUS!
  - o glue
- **Two layers of double sided detectors with 5.5mm min. distance**
  - o bonds
  - o mounting



A=0.5736  
B=5.5863

### Play in between detectors

293 Kelvins





## Gluing of the Bus

Glue: araldite W106 low temperature mixture (50:50)

Temperature cycling (300K-77K-300K)

- Reliable
- Regular
- Repeatable
- no glue on the bond pads!
- no air bubbles (vacuum!)



Commercial glue dispenser

+

Alignment table with microscope



Tests to define:

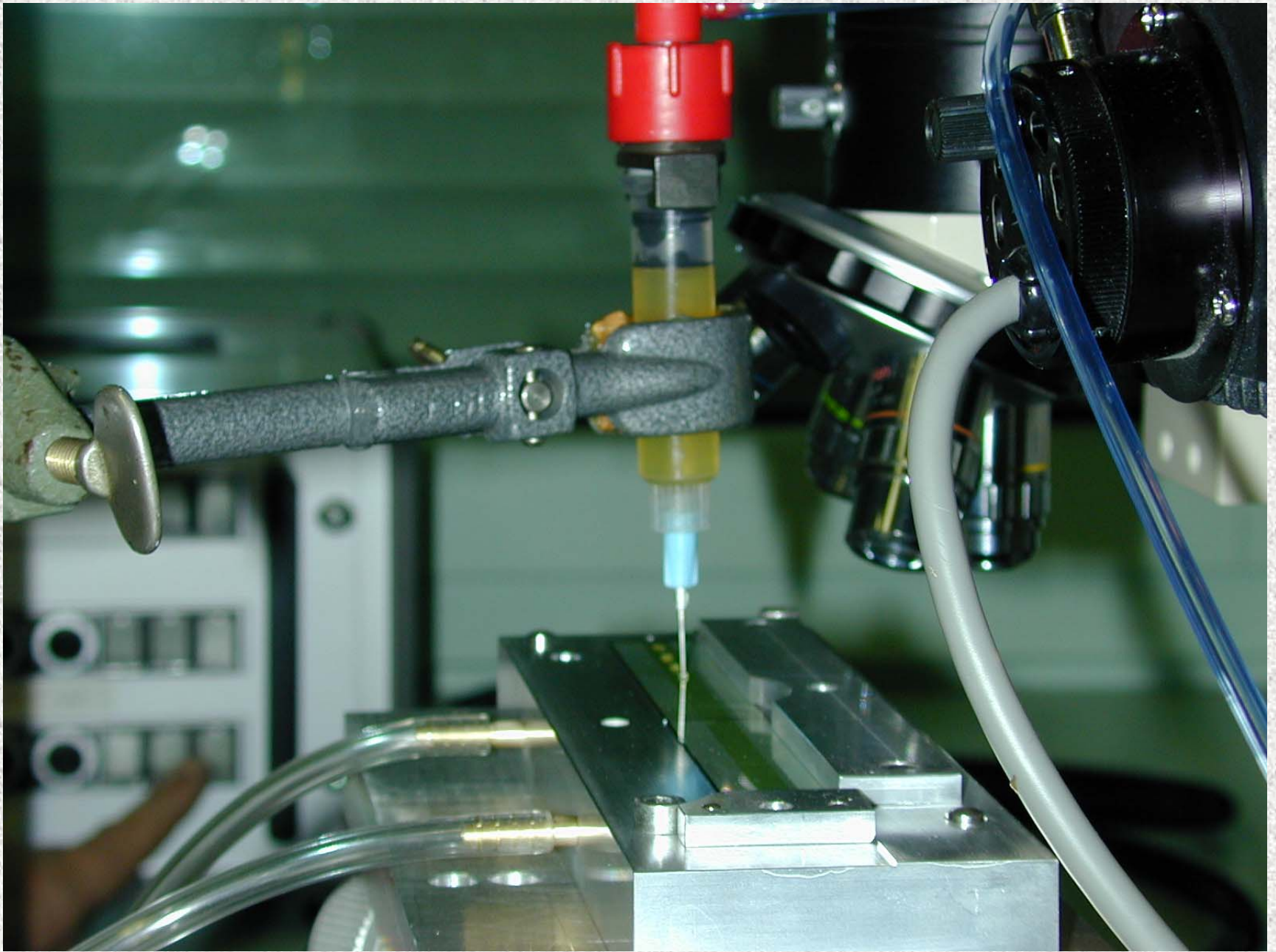
- Duration
- Step width
- Pressure
- Weight

Glass

Silicon









## Finding the right carrier material for the bus

### Production of prototypes:

Prototype 0: 160 mm Si + PCB hybrid + capton (V0)

Prototype 1: 162 mm Si + alumine hybrid + alumine bus (V1)

Prototype 2: 162 mm Si + alumine hybrid + glass (D263) bus (V1)

Prototype 3: 162 mm Si + alumine hybrid + alumine bus (V1)

Prototype 4: 162 mm Si + alumine hybrid + glass (AF45) bus (V1)

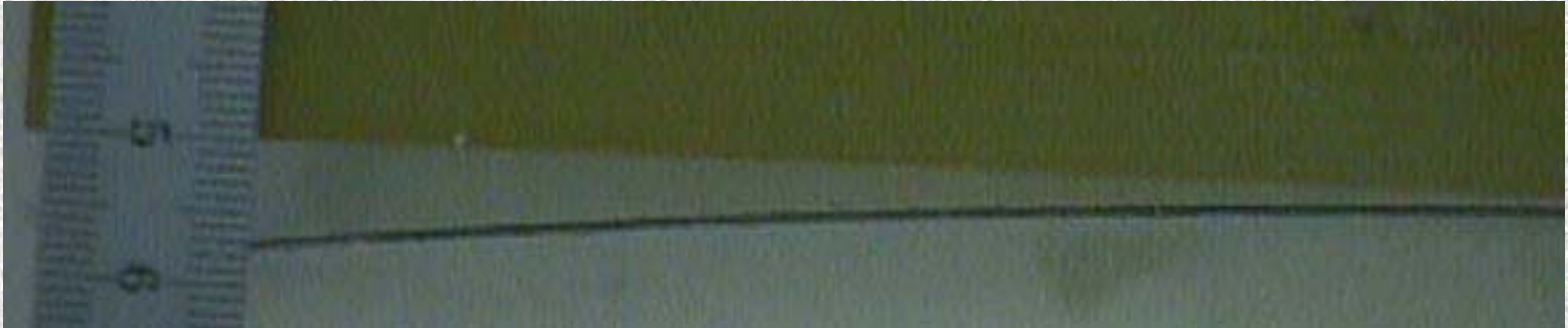
Prototype 5: 162 mm Si + alumine hybrid + carbon bus (V1)

Prototype 6: 162 mm Si + alumine hybrid + silicon bus (V1)



Tests with LN<sub>2</sub> in special low temperature test box with glass window

Alumine bus - prototype seen from the side at LN<sub>2</sub> temperature



Glass bus (D263) - prototype seen from the side at LN<sub>2</sub> temperature





## Thermal expansion coefficients:

Capton	~30 ppm/K
Alumine	6.5-6.7 ppm/K
Glass D263	7.2 ppm/K
Glass AF 45	4.5 ppm/K
Carbon	2.1 ppm/K
<b>Silicon</b>	<b>2.6-4.2 ppm/K</b>

(~40 $\mu$  deviation on full length)

## Bus:

Produced on 200mm Si wafers (400 $\mu$ )  
Water-cooled laser-cutting  
(PREJET AG, CH)





## Bonding on the Bus

Bus provides connection between n+ pads and the hybrid (..pitch adapter..) and is also the support for the two sensors.

### Layout:

40  $\mu\text{m}$  wide lines

Bond pads: 50 $\mu\text{m}$  x 200 $\mu\text{m}$

Pitch: 1248 $\mu\text{m}$  on n+ side, 120 $\mu\text{m}$  on hybrid side

Base material: 8" wafers thinned to 400 $\mu\text{m}$ , coated with polyimide on both sides (~10 $\mu\text{m}$ )

Traces and pads: Chrom+Aluminium

...**bond test fails** - bonds do not stick (varied bonding parameters, plasma etching, bake out,...)



Add Ni-Ti-Au layers onto the bonding pads + plasma etching - Bonding OK





# Summary

- The development and production for the ATHENA SVX took ~ 3 yrs.
- The limited space and the operation at LN2 temperature and in vacuum put serious constraints on the individual components and the assembly.
- A special mechanical support was designed with only one side fixed in order to absorb all the occurring forces during the temperature cycles (90-300 K).
- The help from R. de Oliveira made it possible to produce the silicon bus which provides mechanical support and the electrical contacts for the double sided silicon detectors (bonding!)
- The SVX has been operated successfully for 2 years with a new run period coming up now. In the meantime the detector was warmed up and cooled to ~90K several times.